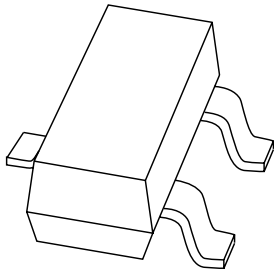


DATA SHEET



PMBT3904 NPN switching transistor

Product data sheet
Supersedes data of 1999 Apr 27

2004 Jan 12

NPN switching transistor

PMBT3904

FEATURES

- Collector current capability $I_C = 200 \text{ mA}$
- Collector-emitter voltage $V_{CEO} = 40 \text{ V}$.

APPLICATIONS

- General switching and amplification.

DESCRIPTION

NPN switching transistor in a SOT23 plastic package.
PNP complement: PMBT3906.

MARKING

TYPE NUMBER	MARKING CODE ⁽¹⁾
PMBT3904	*1A

Note

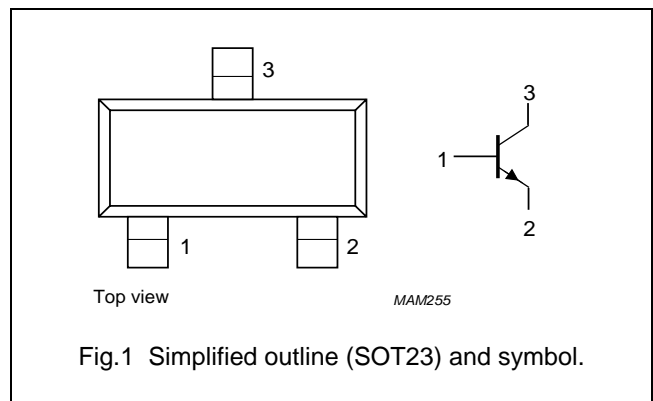
- * = p : Made in Hong Kong.
* = t : Made in Malaysia.
* = W : Made in China.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V_{CEO}	collector-emitter voltage	40	V
I_C	collector current (DC)	200	mA

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PMBT3904	-	plastic surface mounted package; 3 leads	SOT23

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	60	V
V_{CEO}	collector-emitter voltage	open base	–	40	V
V_{EBO}	emitter-base voltage	open collector	–	6	V
I_C	collector current (DC)		–	200	mA
I_{CM}	peak collector current		–	200	mA
I_{BM}	peak base current		–	100	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$; note 1	–	250	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	operating ambient temperature		–65	+150	°C

Note

1. Transistor mounted on an FR4 printed-circuit board.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

$T_{amb} = 25\text{ °C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I_{CBO}	collector cut-off current	$I_E = 0$; $V_{CB} = 30\text{ V}$	–	50	nA
I_{EBO}	emitter cut-off current	$I_C = 0$; $V_{EB} = 6\text{ V}$	–	50	nA
h_{FE}	DC current gain	$V_{CE} = 1\text{ V}$; see Fig.2; note 1 $I_C = 0.1\text{ mA}$ $I_C = 1\text{ mA}$ $I_C = 10\text{ mA}$ $I_C = 50\text{ mA}$ $I_C = 100\text{ mA}$	60 80 100 60 30	– – 300 – –	
V_{CEsat}	collector-emitter saturation voltage	$I_C = 10\text{ mA}$; $I_B = 1\text{ mA}$ $I_C = 50\text{ mA}$; $I_B = 5\text{ mA}$	– –	200 300	mV mV
V_{BEsat}	base-emitter saturation voltage	$I_C = 10\text{ mA}$; $I_B = 1\text{ mA}$ $I_C = 50\text{ mA}$; $I_B = 5\text{ mA}$	650 –	850 950	mV mV
C_c	collector capacitance	$I_E = I_e = 0$; $V_{CB} = 5\text{ V}$; $f = 1\text{ MHz}$	–	4	pF
C_e	emitter capacitance	$I_C = I_c = 0$; $V_{BE} = 500\text{ mV}$; $f = 1\text{ MHz}$	–	8	pF

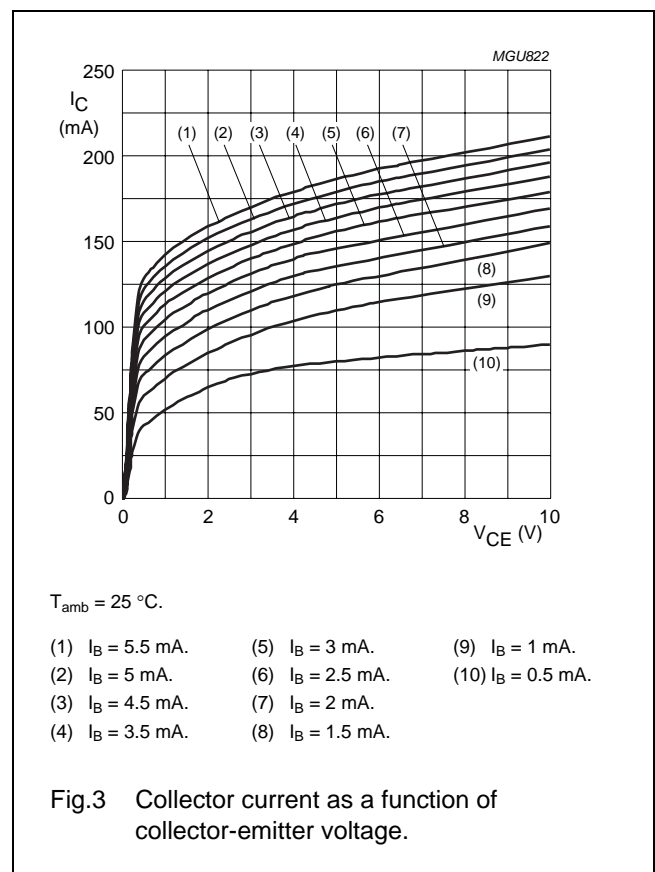
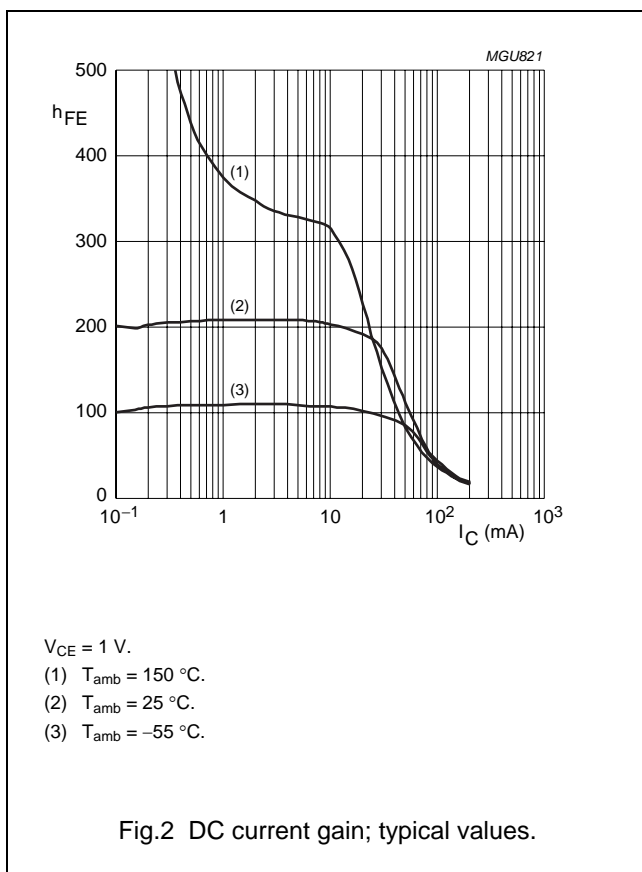
NPN switching transistor

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SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
f_T	transition frequency	$I_C = 10 \text{ mA}; V_{CE} = 20 \text{ V};$ $f = 100 \text{ MHz}$	300	–	MHz
F	noise figure	$I_C = 100 \mu\text{A}; V_{CE} = 5 \text{ V}; R_S = 1 \text{ k}\Omega;$ $f = 10 \text{ Hz to } 15.7 \text{ kHz}$	–	5	dB
Switching times (between 10% and 90% levels); see Fig.3					
t_d	delay time	$I_{Con} = 10 \text{ mA}; I_{Bon} = 1 \text{ mA};$ $I_{Boff} = -1 \text{ mA}$	–	35	ns
t_r	rise time		–	35	ns
t_s	storage time		–	200	ns
t_f	fall time		–	50	ns

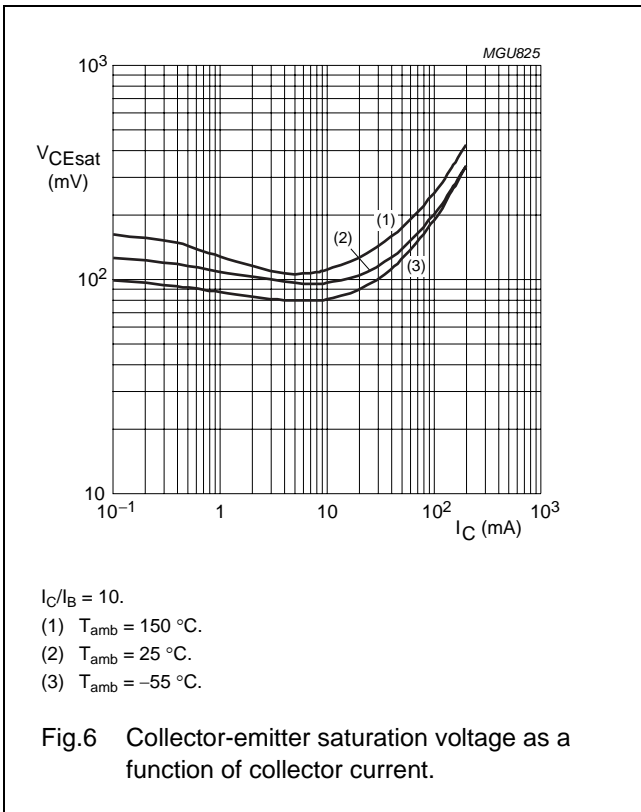
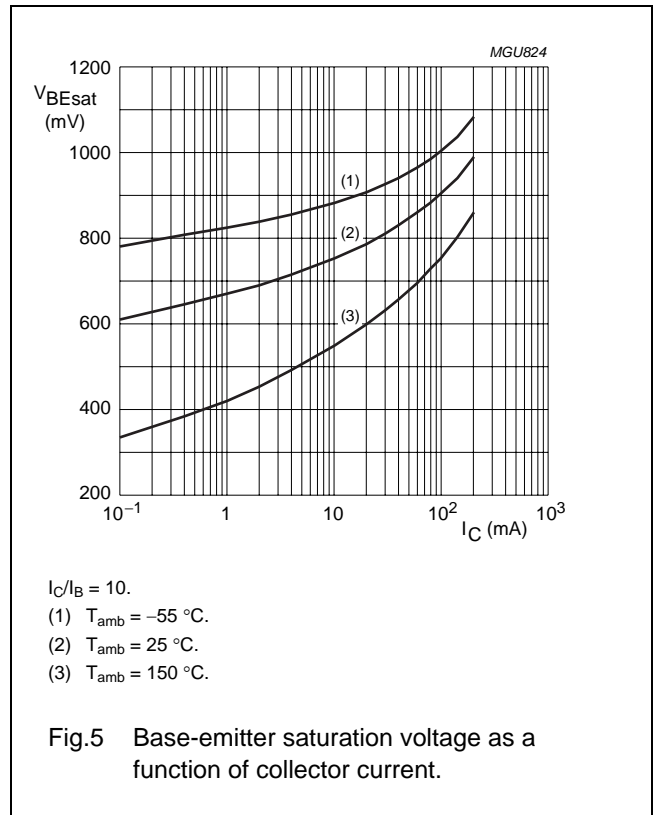
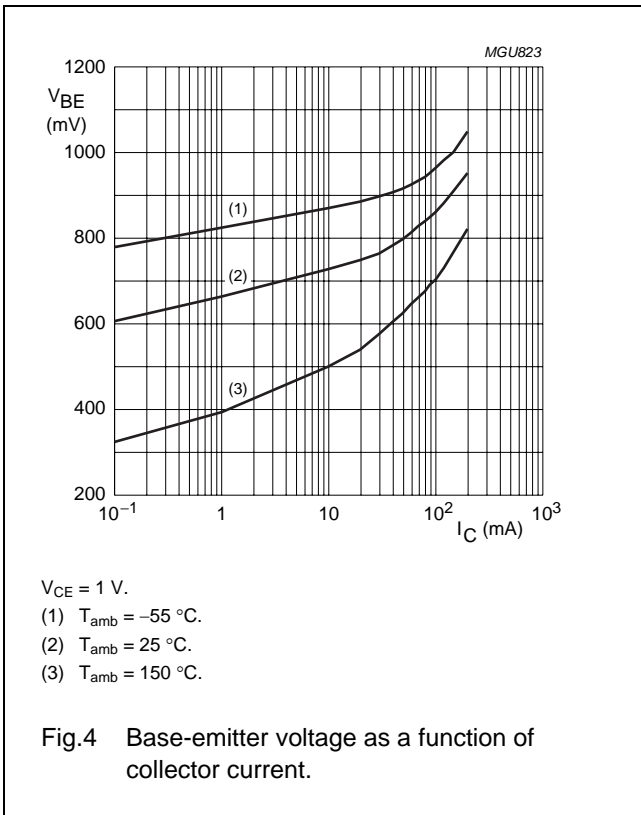
Note

1. Pulse test: $t_p \leq 300 \mu\text{s}; \delta \leq 0.02$.



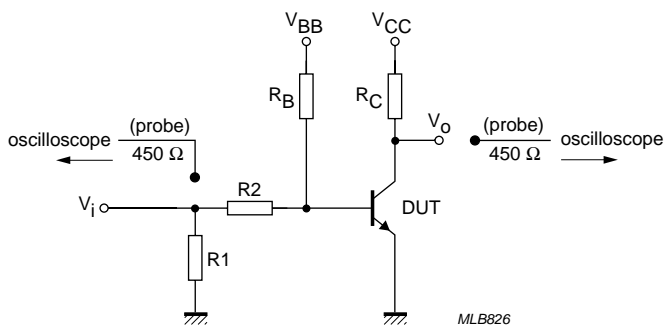
NPN switching transistor

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NPN switching transistor

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$V_i = 5\text{ V}$; $T = 500\ \mu\text{s}$; $t_p = 10\ \mu\text{s}$; $t_r = t_f \leq 3\ \text{ns}$.
 $R_1 = 56\ \Omega$; $R_2 = 2.5\ \text{k}\Omega$; $R_B = 3.9\ \text{k}\Omega$; $R_C = 270\ \Omega$.
 $V_{BB} = -1.9\ \text{V}$; $V_{CC} = 3\ \text{V}$.
 Oscilloscope: input impedance $Z_i = 50\ \Omega$.

Fig.7 Test circuit for switching times.

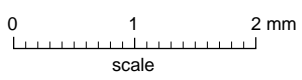
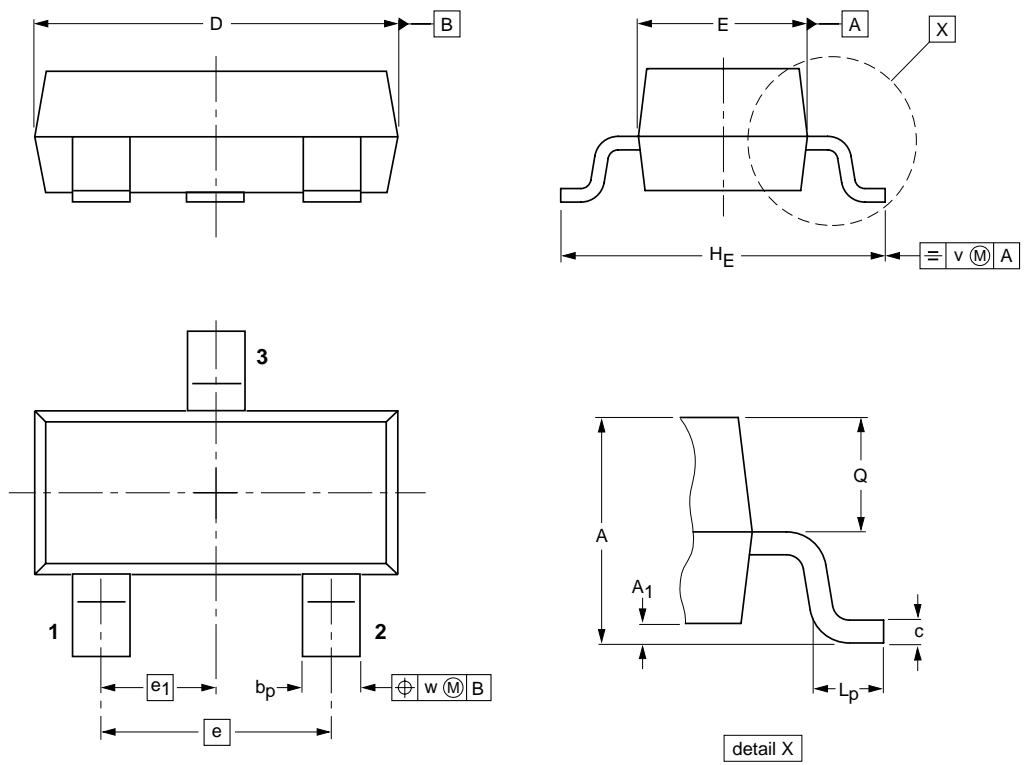
NPN switching transistor

PMBT3904

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads

SOT23



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max.	b _p	c	D	E	e	e ₁	H _E	L _p	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT23		TO-236AB				04-11-04 06-03-16

NPN switching transistor

PMBT3904

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Printed in The Netherlands

R75/04/pp9

Date of release: 2004 Jan 12

Document order number: 9397 750 12461

